## Progress in Analyzing HAPL Tungsten Candidate First Wall Materials

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MADISCN

# Helium Implantation in Tungsten Using the University of Wisconsin IEC Facility



- **Purpose:** To determine the effect of helium implantation on the surface morphology of tungsten coatings at high temperatures
- Why: To see if tungsten can serve as a suitable coating material for the HAPL first wall
- How: Use of high voltages to drive helium ions into tungsten cathodes held at high temperatures (800 to 1,200 °C)

#### UW IEC Chamber has Capability of High-Temperature Implantation at 10-100 kV



D<sup>+</sup>, 20 kV, 5 mA 2 mtorr, 1100 °C



## **Results Since the Last HAPL Meeting**



- Ion implantation fluences were reported about an order of magnitude higher than actual
  - Secondary electron emission was measured and found to be much higher than previously thought
- Single crystal tungsten samples were obtained for future runs
- Experimental measurements reveal porous surface increases emissivity
- Tungsten foam samples were obtained from Ultramet and as-received samples were characterized.
- Initial irradiations have begun (45 kV and  $\approx$ 1,000 °C)

#### Secondary Electron Emission Off the Grid Wires is Much Higher than Expected

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### Helium and Deuterium Fluence Corrections,



#### Helium Fluence Scan (He<sup>+</sup>/cm<sup>2</sup>)

Previous	3x10 <sup>17</sup>	1x10 <sup>18</sup>	$2x10^{18}$	$4x10^{18}$	1x10 <sup>19</sup>
Updated	1x10 <sup>16</sup>	3x10 <sup>16</sup>	1x10 <sup>17</sup>	3x10 <sup>17</sup>	6x10 <sup>17</sup>

Helium Energy (20-80 keV)

#### & Temperature (730-1160 °C) Scans (He<sup>+</sup>/cm<sup>2</sup>)

Undeted	3x10 <sup>-1</sup>	
Opualed	JXIU	

Deuterium Run, 40 kV @ 1200 °C (D+/cm<sup>2</sup>)

Previous	2x10 <sup>19</sup>
Updated	2x10 <sup>18</sup>

#### Threshold for Pore Formation with 30 keV Helium Occurs at <4x10<sup>16</sup> He<sup>+</sup>/cm<sup>2</sup>





#### Temperature Scan Was Performed at 3x10<sup>17</sup> He<sup>+</sup>/cm<sup>2</sup> (5x10<sup>18</sup> Was Reported Before)





#### Irradiation of W at High Temperature With Helium Ions Can Improve the Thermal Emissivity

Thermal Emissivity Coefficient of Tungsten Powder Metallurgy Samples

![](_page_8_Figure_2.jpeg)

#### Jaworske and Beach-NASA Glen Research Center

#### **Tungsten Single Crystal Sample**

![](_page_9_Picture_1.jpeg)

![](_page_9_Picture_2.jpeg)

Tungsten Single Crystal will show how much the lack of grain boundaries will affect the helium pore formation (Obtained from Lance Snead, ORNL)

#### **Tungsten Single Crystal Sample**

![](_page_10_Picture_1.jpeg)

![](_page_10_Picture_2.jpeg)

#### Tungsten-Coated Carbide Foam Samples From Ultramet

![](_page_11_Picture_1.jpeg)

Hafnium Carbide Tungsten Coating

> Tantalum Carbide Tungsten Coating

(front)

(back)

Tantalum Carbide High-Emissivity Tungsten Coating

#### As-Received Foam Tungsten-Coated Carbide Samples From Ultramet

![](_page_12_Picture_1.jpeg)

Hafnium Carbide Foam Tungsten Coating

![](_page_12_Picture_3.jpeg)

Tantalum Carbide Foam Tungsten Coating

![](_page_12_Picture_5.jpeg)

Tantalum Carbide Foam High Emis. Tungsten Surface Coating

![](_page_12_Picture_7.jpeg)

### As-Received Foam Surfaces Are Rough

![](_page_13_Picture_1.jpeg)

Hafnium Carbide Foam Tungsten Coating

![](_page_13_Picture_3.jpeg)

Tantalum Carbide Foam Tungsten Coating

![](_page_13_Picture_5.jpeg)

Tantalum Carbide Foam High Emis. Tungsten Surface Coating

### As-Received Foam Surfaces Are Rough

![](_page_14_Picture_1.jpeg)

#### Hafnium Carbide Foam Tungsten Coating

![](_page_14_Picture_3.jpeg)

#### Tantalum Carbide Foam Tungsten Coating

#### Polished Tungsten Powder Met. Samples

1 µm

Tantalum Carbide Foam High Emis. Tungsten Surface Coating

![](_page_14_Picture_8.jpeg)

# Annealing at 1200 °C for 30 min. has Little Effect on the Foam Surface Morphology

![](_page_15_Picture_1.jpeg)

![](_page_15_Picture_2.jpeg)

W-Coated HfC As-Received

![](_page_15_Picture_4.jpeg)

W-Coated TaC As-Received

![](_page_15_Picture_6.jpeg)

High-ε W-Coated TaC As Received

![](_page_15_Picture_8.jpeg)

W-Coated HfC Annealed

![](_page_15_Picture_10.jpeg)

W-Coated TaC Annealed

![](_page_15_Picture_12.jpeg)

High-e W-Coated TaC Annealed 16

## Conclusions

- Incorporation of higher secondary electron emission required a restatement of helium ion fluences to W samples
  - Implication: Pore formation will occur at <4x10<sup>16</sup> He<sup>+</sup>/cm<sup>2</sup> (30 min. reference HAPL chamber operation)
- Porous W surface can increase thermal emissivity
- As-received morphology of W-coated carbide foam samples have a rough, angular surface
- Annealing of W-coated carbide foam samples to 1,200
  °C causes little change to surface morphology
- Initial tests on W-coated carbide foam samples have been conducted up to 45 kV at 1,000 °C

## **Future Experimental Plans**

![](_page_17_Picture_1.jpeg)

- Determine the threshold for pore formation in single crystal tungsten (at high temperatures) using helium implantation
- Examine D + He effects on morphology of W surfaces bombarded at 1,000 to 1,200 °C
- Run foam samples in the IEC device
- Design pulsing capability into UW IEC facility